

SKCD 18 C 120 I3



CAL-DIODE

$I_{F(DC)} = 25\text{ A}$
 $V_{RRM} = 1200\text{ V}$
 Size: $4.2 \times 4.2\text{ mm}^2$

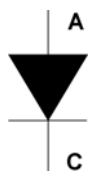
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Features

- low forward voltage drop combined with a low temperature dependence
- easy paralleling due to a small forward voltage spread
- very soft recovery behavior
- small switching losses
- high ruggedness
- compatible to thick wire bonding
- compatible to all standard solder processes

Typical Applications*

- freewheeling diode for IGBT
- particularly suitable for frequencies > 8 kHz



SKCD

Absolute Maximum Ratings

Symbol	Conditions	Values	Unit
V_{RRM}	$T_j = 25\text{ °C}$, $I_R = 0.08\text{ mA}$	1200	V
I_{FSM}	10 ms $\sin 180^\circ$	$T_j = 25\text{ °C}$ $T_j = 150\text{ °C}$	A A
i^2t	$T_j = 150\text{ °C}$, $t_p = 10\text{ ms}$, $\sin 180^\circ$	200	A ² s
T_{jmax}		150	°C

Electrical Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
$I_{F(AV)}$	$T_c = 80\text{ °C}$, $T_j = 150\text{ °C}$, $F_r = PI/2$, Semitrans Assembly; $R_{th(j-c)} = 1.47\text{ K/W}$		18		A
I_R	$T_j = 25\text{ °C}$, $V_{RRM} = 1200\text{ V}$			0.08	mA
	$T_j = 125\text{ °C}$, $V_{RRM} = 1200\text{ V}$			2.00	mA
V_F	$T_j = 25\text{ °C}$, $I_F = 15\text{ A}$		2.00	2.50	V
	$T_j = 125\text{ °C}$, $I_F = 15\text{ A}$		1.79	2.30	V
$V_{(TO)}$	$T_j = 125\text{ °C}$		1.18		V
r_T	$T_j = 125\text{ °C}$		36.7		mΩ

Dynamic Characteristics

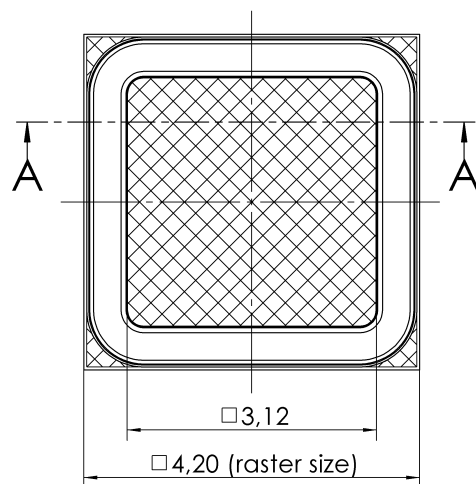
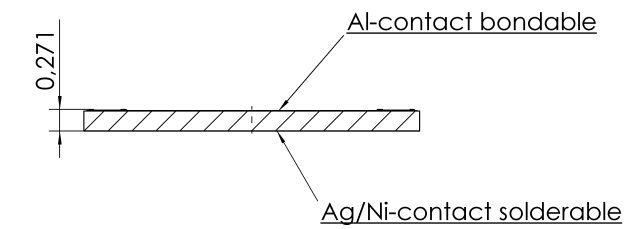
Symbol	Conditions	min.	typ.	max.	Unit
E_{rr}	$T_j = 25\text{ °C}$, 25 A, 600 V, 500 A/μs		0.35		mJ
E_{rr}	$T_j = 125\text{ °C}$, 25 A, 600 V, 500 A/μs		0.92		mJ
Q_{rr}	$T_j = 25\text{ °C}$, 25 A, 600 V, 500 A/μs		1.24		μC
Q_{rr}	$T_j = 125\text{ °C}$, 25 A, 600 V, 500 A/μs		3		μC
I_{rrm}	$T_j = 25\text{ °C}$, 25 A, 600 V, 500 A/μs		13		A
I_{rrm}	$T_j = 125\text{ °C}$, 25 A, 600 V, 500 A/μs		17		A

Thermal Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
T_j		-40		150	°C
T_{stg}		-40		150	°C
T_{solder}	10 min.			250	°C
T_{solder}	5 min.			320	°C

Mechanical Characteristics

Symbol	Conditions	Values	Unit
Raster size		4.2×4.2	mm ²
Area total		17.64	mm ²
Anode		bondable (Al)	
Cathode		solderable (Ag/Ni)	
Wire bond		Al, diameter ≤ 500 μm	
Package		150 mm wafer frame	
Chips / Package		848	pcs



die size after cutting
□ 4,17 mm

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.